

## **LOCTITE ABLESTIK 2025D**

**April 2014** 

#### PRODUCT DESCRIPTION

LOCTITE ABLESTIK 2025D provides the following product characteristics:

Technology	Dransiator, Hubrid Chamietry		
reclinology	Proprietary Hybrid Chemistry		
Appearance	red		
Cure	Heat cure		
Product Benefits	Minimum bleed		
	<ul> <li>Good adhesion to a variety of substrates</li> </ul>		
	<ul> <li>High hot/wet die shear strength</li> </ul>		
	<ul> <li>260°C reflow capability for Pb-free applications</li> </ul>		
	<ul> <li>Non-conductive</li> </ul>		
Application	Die attach		
Filler Type	Silica		
Typical Package Application	PBGA, FlexBGA and Stacking BGA		

LOCTITE ABLESTIK 2025D die attach adhesive is designed for use in array packaging.

#### TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	4.4
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	11,500
Work Life by Gel Time, hours:	
@ 25°C, 30cc syringe	16
@ 25°C, 10cc syringe	24
Shelf Life @ -40°C (from date of manufacture), days	365

#### **TYPICAL CURING PERFORMANCE**

#### **Cure Schedule**

30 minute ramp to 175°C + 15 minutes @ 175°C

#### Weight Loss on Cure

10 x 10 mm Si die on glass slide %	2.5
10 x 10 mm St die on diass stide %	2.5

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

#### TYPICAL PROPERTIES OF CURED MATERIAL

#### **Physical Properties**

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Coefficient of Thermal Expansion ppm/°C:		
Below Tg, ppm/°C	48	
Above Tg, ppm/°C	140	
Glass Transition Temperature (Tg) by TMA, °C:		
Post Mold	42	
Post Cure	-37	
Thermal Conductivity, W/(m-K)	0.4	

Tensile Modulus, DMTA:		
@ 25 °C	N/mm²	
	(psi)	(59,000)
@ 100 °C	N/mm²	
	(psi)	(8,400)
@ 150 °C	N/mm²	• •
	(psi)	(6,000)
@ 200 °C	N/mm²	65
	(psi)	(9,500)
@ 250 °C	N/mm²	116
	(psi)	(16,800)
@ 300 °C	N/mm²	
	(psi)	(26,200)
Extractable Ionic Content, ppm:		
Chloride (CI-)		<10
Sodium (Na+)		<10
Potassium (K+)		<10
Moisture Absorption @ Saturation, after 8 RH exposure, wt %	35°C/85%	0.58

#### TYPICAL PERFORMANCE OF CURED MATERIAL

#### Miscellaneous

Die Shear Strength:		
2 X 2 mm (80 x 80 mil) Si die on PBGA, kg-f:		
@ 25 °C	10	
3 X 3 mm (120 x 120 mil) Si die on PBGA, kg-f:		
@ 25 °C	20	
@ 260°C	3.5	
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Chip Warpage vs Chip Size:

12.7 x 12.7 mm (500 x 500 mil), 0.38 mm (15 mil) thick Si die: On 0.2 mm (8 mil) thick Ag/Cu LF @ 25°C, µm 19

#### **GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

#### Thawing:

- 1. Allow container to reach room temperature before use.
- After removing from the freezer, set the syringes to stand vertically while thawing.
- DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.



#### **DIRECTIONS FOR USE**

- Thawed adhesive should immediately be placed on dispense equipment for use.
- If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
- Adhesive must be completely used within the product's recommended work life.
- Apply enough adhesive to achieve a 25 to 50 µm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
- Alternate dispense amounts may be used depending on the application requirements.
- Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

#### Disclaimer

#### Note:

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